Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **+ V**
2. **Vztot**
3. **V –**
4. **Vz +**
5. **COM SENSE**
6. **COM FORCE**
7. **TRIM**
8. **OUT**
9. **FB**
10. **NOISE**

**REDUCTION**



**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size: .0046” X .0046”**

**Backside Potential:**

**Mask Ref: CIC01635**

**APPROVED BY: DK DIE SIZE .055” X .075” DATE: 8/25/21**

**MFG: TEXAS INSTRUMENTS THICKNESS .024” P/N: REF102**

**DG 10.1.2**

#### Rev B, 7/19/02